

Title (en)  
COPPER-ZINC ALLOY ELECTROPLATING BATH AND PLATING METHOD USING THE COPPER-ZINC ALLOY ELECTROPLATING BATH

Title (de)  
GALVANISIERUNGSBAD AUS KUPFER-ZINK-LEGIERUNG UND PLATTIERUNGSVERFAHREN MIT DEM GALVANISIERUNGSBAD AUS KUPFER-ZINK-LEGIERUNG

Title (fr)  
BAIN D'ÉLECTRODÉPOSITION D'ALLIAGE CUIVRE-ZINC ET PROCÉDÉ DE DÉPOSITION UTILISANT LE BAIN D'ÉLECTRODÉPOSITION D'ALLIAGE CUIVRE-ZINC

Publication  
**EP 2218804 A4 20110824 (EN)**

Application  
**EP 08854020 A 20081126**

Priority  
• JP 2008071470 W 20081126  
• JP 2007304377 A 20071126  
• JP 2007304376 A 20071126

Abstract (en)  
[origin: EP2218804A1] A cyanide-free copper-zinc alloy electroplating bath is provided which can form a uniform and glossy alloy layer having the desired composition even at a higher current density than that for a conventional electroplating bath, and which is excellent in productivity. The copper-zinc alloy electroplating bath comprises at least one selected from a copper salt, zinc salt, alkali metal pyrophosphate, and amino acid or a salt thereof, and has a pH of 8.5 to 14. The pH is preferably 10.5 to 11.8; and the concentration of the amino acid or a salt thereof is preferably 0.08 mol/L to 0.22 mol/L, more preferably 0.1 mol/L to 0.13 mol/L. As the amino acid or a salt thereof, histidine or a salt thereof may be preferably used.

IPC 8 full level  
**C25D 3/58** (2006.01)

CPC (source: EP US)  
**C25D 3/58** (2013.01 - EP US); **C25D 3/38** (2013.01 - EP US)

Citation (search report)  
• No further relevant documents disclosed  
• See references of WO 2009069669A1

Citation (examination)  
• EP 0752484 A1 19970108 - PIRELLI [IT]  
• GB 1498212 A 19780118 - MCGEAN CHEM CO INC  
• SENNA L F ET AL: "ELECTRODEPOSITION OF COPPER-ZINC ALLOYS IN PYROPHOSPHATE-BASED ELECTROLYTES", JOURNAL OF APPLIED ELECTROCHEMISTRY, SPRINGER, DORDRECHT, NL, vol. 33, no. 12, 1 December 2003 (2003-12-01), pages 1155 - 1161, XP001211549, ISSN: 0021-891X, DOI: 10.1023/B:JACH.00000003756.11862.6E

Cited by  
US10561638B2

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)  
**EP 2218804 A1 20100818; EP 2218804 A4 20110824**; CN 101874128 A 20101027; CN 101874128 B 20120704; US 2010243466 A1 20100930; WO 2009069669 A1 20090604

DOCDB simple family (application)  
**EP 08854020 A 20081126**; CN 200880117760 A 20081126; JP 2008071470 W 20081126; US 74464108 A 20081126